Material Declaration Report

Package Type:	**SSOP 20L**
Pericom Package Code:	**H20(Pb-free)**
RoHS Compliance:	**Yes**
Applicable Exemption:	**N/A**

Component Weight (mg):	**165.800**
Termination Plating:	**Matte Tin**
JESD 97 Pb-free Category:	**e3**
Plating Thickness (um):	**10~20**
Tin Whisker Mitigation:	**Anneal, 150C/1hr**

MSL Rating:	**1**
Peak Body Temp (C):	**260**
Max Time (sec):	**30**
Reflow Cycles:	**3**
Rev Date:	**6/4/2008**

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	109.611	OSE	Silica Fused	60676-86-0	90.800	99.5264
			Epoxy Resin 1	Proprietary	3.000	3.2883
			Phenolic Resin	Proprietary	3.000	3.2883
			Epoxy Resin 2	Proprietary	2.000	2.1922
			Aromatic Phosphate	Proprietary	1.000	1.0961
			Carbon Black	1333-86-4	0.200	0.2192
		UTL	Silica Fused	60676-86-0	88.000	96.4573
			Epoxy Resin	Proprietary	5.000	5.4805
			Phenolic Resin	Proprietary	4.500	4.9325
			Epoxy, Cresol Novolac	29690-82-2	2.000	2.1922
			Carbon Black	1333-86-4	0.500	0.5481
LEADFRAME	44.336		Copper	7440-50-8	97.021	43.0149
			Iron	7439-89-6	2.350	1.0419
			Silver	7440-22-4	0.453	0.2010
			Zinc	7440-66-6	0.111	0.0491
			Phosphorus	7723-14-0	0.065	0.0288
SILICON DIE	1.925		Silicon (Si)	7440-21-3	99.192	1.9092
			Non-hazardous Metal	Proprietary	0.808	0.0156
DIE ATTACH EPOXY	0.688	OSE	Silver	7440-22-4	76.000	0.5230
			Acrylic Resin	Proprietary	8.000	0.0550
			Acrylate	Proprietary	5.500	0.0378
			Polybutadiene derivative	Proprietary	5.500	0.0378
			Epoxy resin	Proprietary	2.500	0.0172
			Additive	Proprietary	1.000	0.0069
			Butadiene copolymer	Proprietary	1.000	0.0069
			Peroxide	Proprietary	0.500	0.0034
		UTL	Silver	7440-22-4	80.000	0.5505
			Functionalized Urethane	72869-86-4	8.000	0.0550
			Diester Resin	94-80-4	7.000	0.0482
			Epoxy Resin	Proprietary	5.000	0.0344
GOLD WIRE	0.590		Gold(Au)	7440-57-5	99.990	0.5897
			Impurities	-	0.010	0.0001
SOLDER PLATING	8.651		Tin (Sn)	7440-31-5	99.990	8.6500
			Impurity	-	0.010	0.0009

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

	MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Device	Mold Compound	<2	<2	<2	<2	<5	<5
	Leadframe	<50	<2	<2	<2	<5	<5
	Silicon Die	<2	<2	<2	<2	<5	<5
	Die Attach Epoxy	<2	<2	<2	<2	<5	<5
	Gold Wire	<2	<2	<2	<2	<5	<5
	Solder Plating	<50	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC

and

China RoHS Directive SJ/T11363-2006

Declaration Statement: Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium

Pb	Hg	Cr+6	Cd	PBB	PBDE
<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm
O	O	O	O	O	O

O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.

X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.